

MITSUBISHI ELECTRIC GaAs HEMT & FET

4pin flat lead package, Micro-X type plastic package, Leadless ceramic package, Micro-X package

QL-1104E-F

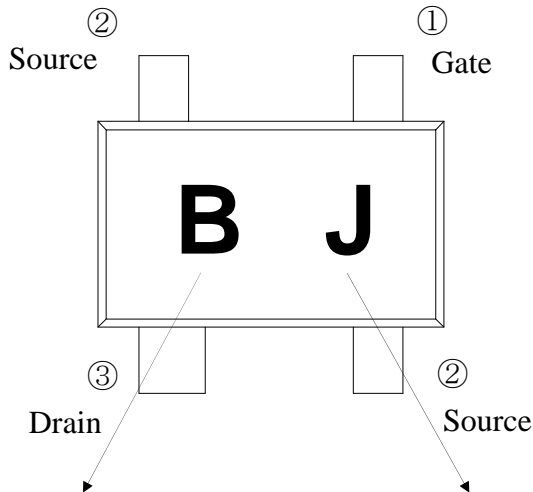
Marking manner of MITSUBISHI ELECTRIC GaAs HEMT & FET

Contents:

1. 4pin flat lead package : GD-30 (MP)
2. Micro-X type plastic package : GD-32 (Not recommended)
3. Leadless ceramic package : GD-26,27 (EOL)
4. Micro-X package (EOL)
5. Micro-X package : GD-31 (EOL)

1. 4pin flat lead packaged device : GD-30 (MP)

Top view



Electrodes direction:

- ① Gate
- ② Source
- ③ Drain



Type

Letter	Product
B	MGF4934BM
C	MGF4921AM
D	MGF4934CM
E	MGF4935AM
H	MGF3022AM
J	MGF4965BM
K	MGF4937AM
L	MGF4938AM

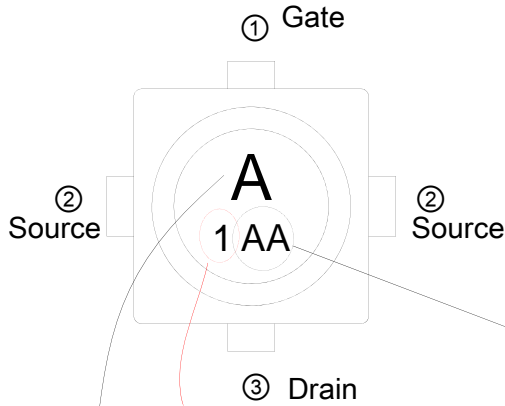
The production year and month

	CY2017	CY2018	CY2019	CY2020	CY2021
Jan.	9	L	Y	s	9
Feb.	0	M	Z	t	0
Mar.	A	N	a	u	Back to "A"
Apr.	B	P	b	v	
May	C	Q	c	1	
Jun.	D	R	d	2	
Jul.	E	S	e	3	
Aug.	F	T	h	4	
Sep.	G	U	k	5	
Oct.	H	V	m	6	
Nov.	J	W	n	7	
Dec.	K	X	r	8	

Production year and month are indicated using numbers and alphabet. Right side character rounds once 4 years.

2. Micro-X type plastic package : GD-32 (Not recommended)

Top view



Electrodes direction:

- ① Gate
- ② Source
- ③ Drain



lot number in month.
'AA, AB, AC, AD,,,AZ, BA, BB,,,'

Type

Letter	Type
A	MGF4941AL
E	MGF4941CL-01
H	MGF4964BL
P	MGF4841CL-01
S	MGF4941CL-40
T	MGF4841AL

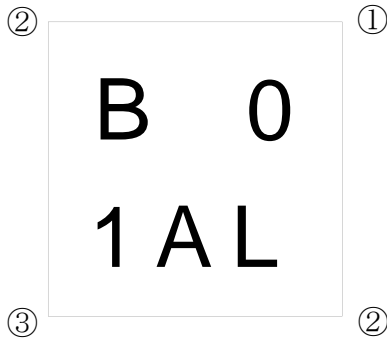
The production year and month

	CY2017	CY2018	CY2019	CY2020	CY2021
Jan.	9	L	Y	s	9
Feb.	0	M	Z	t	0
Mar.	A	N	a	u	Back to "A"
Apr.	B	P	b	v	
May	C	Q	c	1	
Jun.	D	R	d	2	
Jul.	E	S	e	3	
Aug.	F	T	h	4	
Sep.	G	U	k	5	
Oct.	H	V	m	6	
Nov.	J	W	n	7	
Dec.	K	X	r	8	

Production year and month are indicated using numbers and alphabet. Right side character rounds once 4 years.

3. Leadless ceramic package : GD-26,27 (EOL)

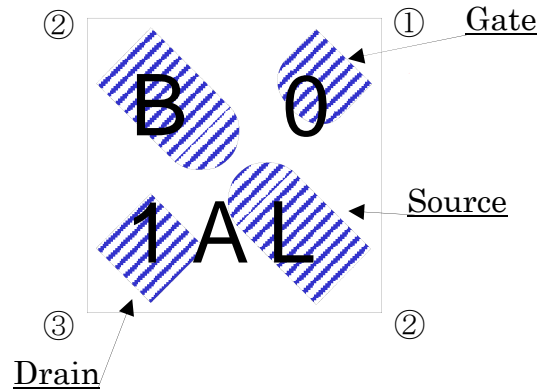
Top view



Electrodes direction:

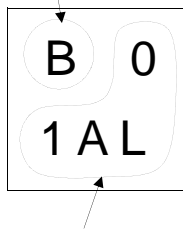
- ① Gate
- ② Source
- ③ Drain

Terminal position (from top view)



Type

Letter	Type
A	<u>MGF4951A/52A</u>
B	<u>MGF4953A/54A</u>
C	<u>MGF1951A</u>
D	<u>MGF1952A</u>
E	<u>MGF1953A</u>
F	<u>MGF1954A</u>
G	<u>MGF4851A</u>
J	<u>MGF4953B</u>



Manufacturing lot number

“01AL”:

‘0’ means year 2000 & 2010. (8: 2008, 9: 2009,,,1: 2011,,,))

‘1’ means April (1:Apr. 2:May, ,, 9:Dec., X:Jan, Y:Feb, Z:Mar.)

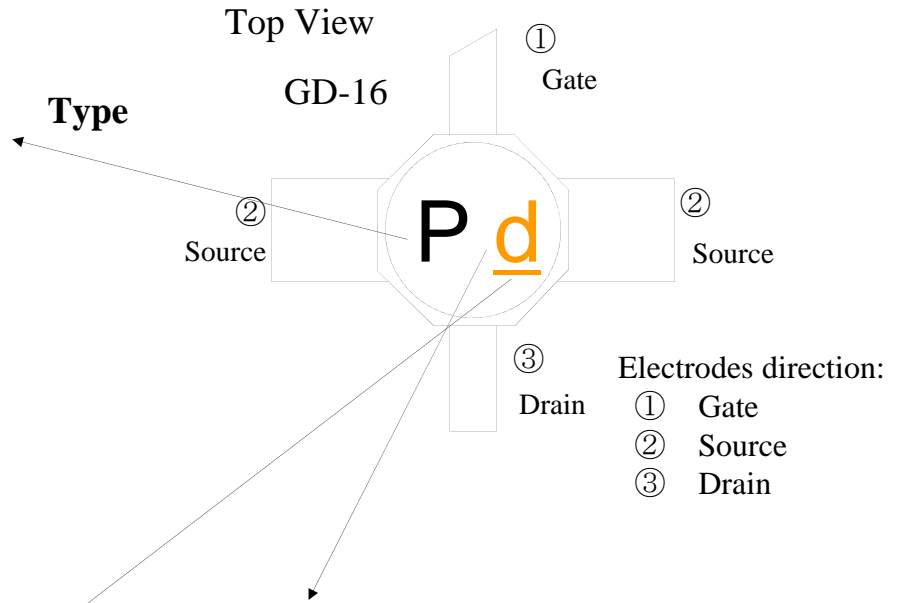
‘AL’ means lot number in month. ‘AA, AB, AC, AD ,,,AZ, BA,,,’

4. Micro-X package (EOL)

Left side character indicates the type number.

Right side character, bottom bar and the color indicate manufacturing year and month.

Type	Symbol	Outline
MGF1302	A	GD-4
MGF1303B	G	
MGF1451A	T	
MGF1402B	J	GD-9
MGF1403B	L	
MGF1601B	E	GD-11
MGF1801B	D	
MGF1801BT	D	GD-24
MGF1907A	P	GD-16
MGF1908A	R	



Bottom bar and color indicate manufacturing month

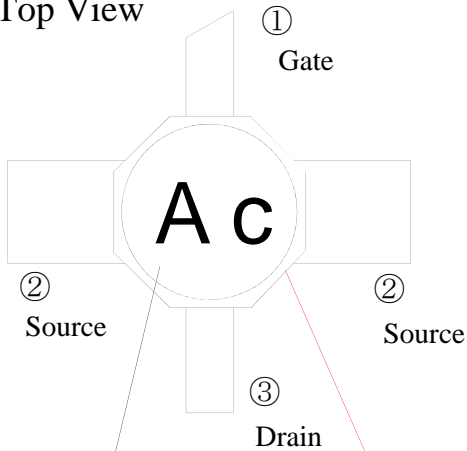
	Without bottom bar	With bottom bar
Blue	Apr.	<u>Oct.</u>
Orange	May	<u>Nov.</u>
Black	June	<u>Dec.</u>
Red	July	<u>Jan.</u>
Green	Aug.	<u>Feb.</u>
Brown	Sep.	<u>Mar.</u>

Fiscal year (FY)

year	Symbol	year	Symbol	year	Symbol
'90	g	'00	s	'10	c
'91	h	'01	t	'11	d
'92	j	'02	u	'12	e
'93	k	'03	v	'13	f
'94	l	'04	w	'14	g
'95	m	'05	x	'15	h
'96	n	'06	y	back to "j"	
'97	p	'07	z		
'98	q	'08	a		
'99	r	'09	b		

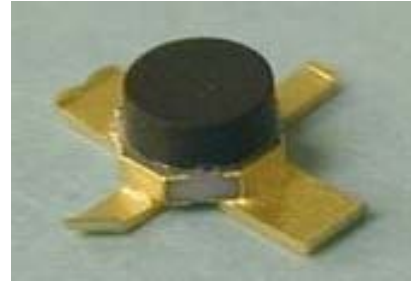
5. Micro-X package : GD-31 (EOL)

Top View



Electrodes direction:

- ① Gate
- ② Source
- ③ Drain



Type

Letter	Type
A	MGF4961B

The production year and month

CY2008		CY2009		CY2010		CY2011		CY2012	
Month	Symbol	Month	Symbol	Month	Symbol	Month	Symbol	Month	Symbol
Jan.	s	Jan.	9	Jan.	L	Jan.	Y	Jan.	s
Feb.	t	Feb.	0	Feb.	M	Feb.	Z	Feb.	t
Mar	u	Mar	A	Mar	N	Mar	a	Mar	u
Apr	v	Apr	B	Apr	P	Apr	b	Apr	v
May	1	May	C	May	Q	May	c	May	
Jun	2	Jun	D	Jun	R	Jun	d	Jun	back to "1"
Jul	3	Jul	E	Jul	S	Jul	e	Jul	
Aug	4	Aug	F	Aug	T	Aug	h	Aug	
Sep	5	Sep	G	Sep	U	Sep	k	Sep	
Oct	6	Oct	H	Oct	V	Oct	m	Oct	
Nov	7	Nov	J	Nov	W	Nov	n	Nov	
Dec	8	Dec	K	Dec	X	Dec	r	Dec	

Production year and month are indicated using numbers and alphabet.
Right side character rounds once 4 years.

Keep safety first in your circuit designs!

Mitsubishi Electric Corporation puts the maximum effort into making semiconductor products better and more reliable, but there is always the possibility that trouble may occur with them. Trouble with semiconductors may lead to personal injury, fire or property damage. Remember to give due consideration to safety when making your circuit designs, with appropriate measures such as (i) placement of substitutive, auxiliary circuits, (ii) use of non-flammable material or (iii) prevention against any malfunction or mishap.

Notes regarding these materials

- These materials are intended as a reference to assist our customers in the selection of the Mitsubishi semiconductor product best suited to the customer's application; they do not convey any license under any intellectual property rights, or any other rights, belonging to Mitsubishi Electric Corporation or a third party.
- Mitsubishi Electric Corporation assumes no responsibility for any damage, or infringement of any third-party's rights, originating in the use of any product data, diagrams, charts, programs, algorithms, or circuit application examples contained in these materials.
- All information contained in these materials, including product data, diagrams, charts, programs and algorithms represents information on products at the time of publication of these materials, and are subject to change by Mitsubishi Electric Corporation without notice due to product improvements or other reasons. It is therefore recommended that customers contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for the latest product information before purchasing a product listed herein.
The information described here may contain technical inaccuracies or typographical errors. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability, or other loss rising from these inaccuracies or errors.
Please also pay attention to information published by Mitsubishi Electric Corporation by various means, including the Mitsubishi Semiconductor home page (<http://www.MitsubishiElectric.com/>).
- When using any or all of the information contained in these materials, including product data, diagrams, charts, programs, and algorithms, please be sure to evaluate all information as a total system before making a final decision on the applicability of the information and products. Mitsubishi Electric Corporation assumes no responsibility for any damage, liability or other loss resulting from the information contained herein.
- Mitsubishi Electric Corporation semiconductors are not designed or manufactured for use in a device or system that is used under circumstances in which human life is potentially at stake. Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor when considering the use of a product contained herein for any specific purposes, such as apparatus or systems for transportation, vehicular, medical, aerospace, nuclear, or undersea repeater use.
- The prior written approval of Mitsubishi Electric Corporation is necessary to reprint or reproduce in whole or in part these materials.
- If these products or technologies are subject to the Japanese export control restrictions, they must be exported under a license from the Japanese government and cannot be imported into a country other than the approved destination.
Any diversion or re-export contrary to the export control laws and regulations of Japan and/or the country of destination is prohibited.
- Please contact Mitsubishi Electric Corporation or an authorized Mitsubishi Semiconductor product distributor for further details on these materials or the products contained therein.